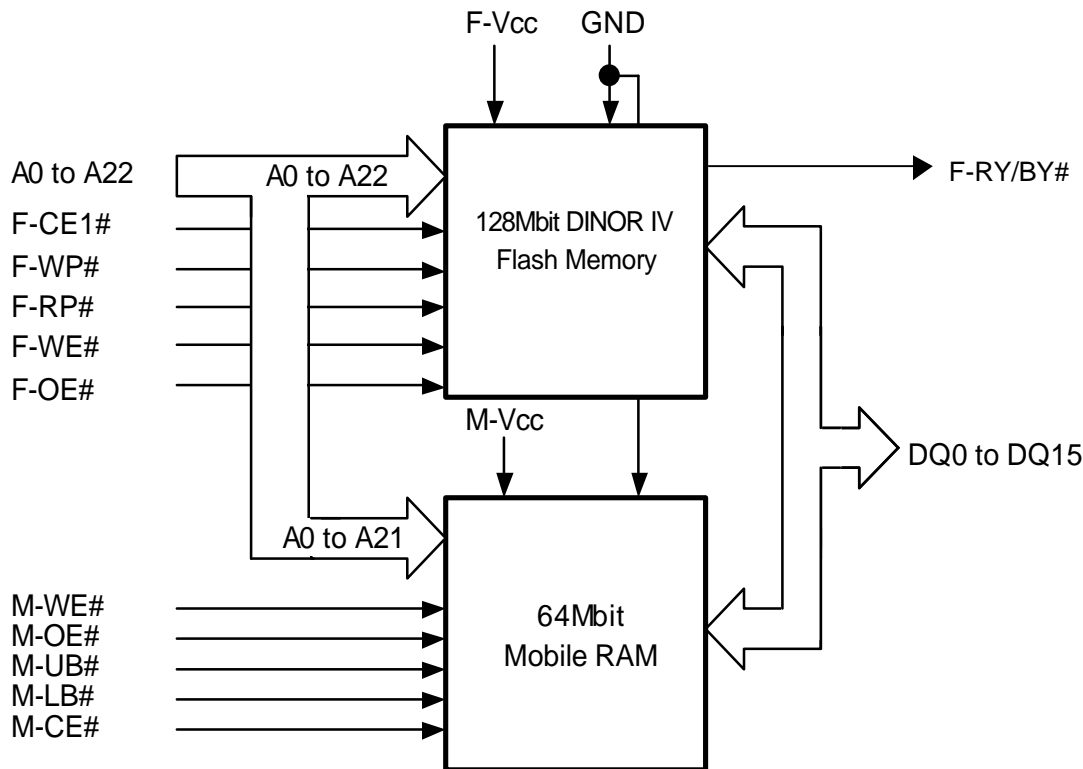


Notice: This is not a final specification.
Some parametric limits are subject to change.

M6MGE13VW66CWG

134,217,728-BIT (8,388,608-WORD BY 16-BIT) CMOS FLASH MEMORY &
67,108,864-BIT (4,194,304-WORD BY 16-BIT) CMOS MOBILE RAM
Stacked-CSP (Chip Scale Package)

MCP Block Diagram



Note: In the Flash Memory part they mean OE# and WE# are F-OE# and F-WE#.
In the Mobile RAM part UB# , LB# , OE# and WE# are M-UB# , M-LB# , M-OE# and M-WE# , respectively.

Capacitance

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
CIN	Input capacitance A21-A0, F-OE#, F-WE#, F-CE1#, F-CE2#, F-WP#, F-RP#, M-OE#, M-WE#, M-CE#, M-LB#, M-UB#	Ta=25°C, f=1MHz, Vin=Vout=0V			26	pF
COUT	Output Capacitance DQ15-DQ0, F-RY/BY#				34	pF

Preliminary

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M6MGE13VW66CWG

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